



1. Material: Four layer, FR4 glass epoxy laminate, 0.062' +/-0.007' thick.
1 oz. copper clad - external layers. 1 oz. copper clad - internal layers.
Material to be RoHS compliant.
2. Plated thru holes and the conductive pattern electroplated with 0.001' min.
thick copper. Terminal areas and plated thru holes to be ENIG plated.
Soldermask over bare copper.
3. Finished Board to be RoHS Compliant
4. Datum for (x,y) co-ordinate drill files at this hole.
5. Processing tolerances:
 - A. Conductive pattern front to back registration within .005' total.
 - B. Minimum annular ring surrounding holes: 0.002'
 - C. Finished conductive pattern within .002' of true size.
6. Warp and twist within .010 inch per inch
7. Dimensions are for the finished part.
8. Solder Mask: Liquid photo imagable solder mask over bare copper (smobc),
colour green, both sides using the patterns provided. No mask is permitted
on the terminal areas. Soldermask to etch registration within .005' total.
9. Screening: Screen component outlines and nomenclature using indelible white
ink on the primary and secondary sides (as required). Nomenclature shall be
legible. Screen to etch registration within .020' total.
10. Surfaces: Punched or machined surfaces 125 micro inches rms max.
11. Break all sharp edges .015' R max.
12. Manufacturer to add ID, UL Vendor Number and Date Code (YY/WW format)
in this area on the component side silkscreen.

SIZE	QTY	SYM	PLATED	TOL
1.0414	6	+ ^L	YES	+/-2.0
1.524	16	+ ^M	YES	+/-0.0
1	11	+ ^N	YES	+/-0.0
0.9398	26	+ ^O	YES	+/-0.0
1.27	2	+ ^P	NO	+/-0.0
2.7	2	+ ^Q	NO	+/-0.0
0.35	338	+ ^R	YES	+/-0.0
0.6	6	+ ^S	YES	+/-0.0